

### STW26NM50-VB Datasheet

N-Channel 500V (D-S) Super Junction Power MOSFET

| PRODUCT SUMMA                              | RY              |       |
|--|-----------------|-------|
| V <sub>DS</sub> (V) at T <sub>J</sub> max. | 500             | )     |
| R <sub>DS(on)</sub> at 25 °C (Ω)           | $V_{GS} = 10 V$ | 0.085 |

### **FEATURES**

- Low figure-of-merit (FOM) Ron x Qg
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Qg)
- Avalanche energy rated (UIS)

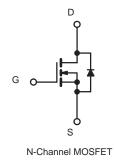
### **APPLICATIONS**

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting



TO-247

Top View



| ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub>                  | = 25 °C, unl                                   | less otherwis   | se noted)                         |             |       |
|---|--|---|-----------------------------------|-------------|-------|
| PARAMETER   |  | SYMBOL  | LIMIT                             | UNIT        |       |
| Drain-Source Voltage                                      |  | V <sub>DS</sub>   | 500                               | v           |       |
| Gate-Source Voltage                                       |  |   | V <sub>GS</sub>                   | ± 30        | v     |
| Continuous Drain Current (T <sub>J</sub> = 150 °C)        | V <sub>GS</sub> at 10 V                        | $T_{\rm C} = 25 \ ^{\circ}{\rm C}$<br>$T_{\rm C} = 100 \ ^{\circ}{\rm C}$ | I.,                               | 33          |       |
| Continuous Drain Current (1) = 150°C)                     | $T_{\rm GS}$ at 10 V $T_{\rm C} = 100^{\circ}$ | T <sub>C</sub> = 100 °C   | I <sub>D</sub>                    | 20          | А     |
| Pulsed Drain Current <sup>a</sup>                         | rain Current <sup>a</sup> I <sub>DM</sub> 100  |   | 100                               | 7           |       |
| Linear Derating Factor                                    |  |   |                                   | 1.67        | W/°C  |
| Single Pulse Avalanche Energy <sup>b</sup>                |  | E <sub>AS</sub>   | 980                               | mJ          |       |
| Maximum Power Dissipation                                 |  | PD  | 310                               | W           |       |
| Operating Junction and Storage Temperature Range          | е  |   | T <sub>J</sub> , T <sub>stg</sub> | -55 to +150 | °C    |
| Drain-Source Voltage Slope                                | $T_J = f$                                      | 125 °C  | d\//dt                            | 50          | 1//22 |
| everse Diode dV/dt <sup>d</sup>                           |  | dV/dt   | 15                                | V/ns        |       |
| Soldering Recommendations (Peak Temperature) <sup>c</sup> | for  | 10 s  |                                   | 260         | °C    |

#### Notes

a. Repetitive rating; pulse width limited by maximum junction temperature. b.  $V_{DD} = 100 \text{ V}$ , starting  $T_J = 25 \text{ °C}$ , L = 30mH,  $R_g = 25 \Omega$ ,  $I_{AS} = 16A$ .

c. 1.6 mm from case.

d.  $I_{SD} \leq I_D$ , dl/dt = 100 A/µs, starting  $T_J$  = 25 °C.

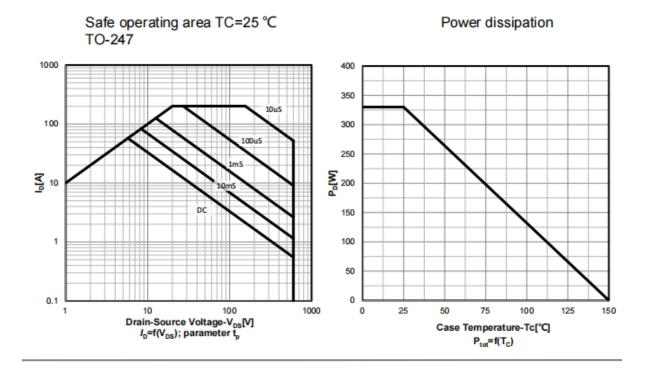


| THERMAL RESISTANCE RATI                                    | NGS                   |  |                                      |                              |      |       |       |          |
|--|-----------------------|--|--------------------------------------|------------------------------|------|-------|-------|----------|
| PARAMETER  | SYMBOL                | TYP.   |                                      | MAX.                         |      |       | UNIT  |          |
| Maximum Junction-to-Ambient                                | R <sub>thJA</sub>     | -  |                                      | 62                           |      |       |       |          |
| Maximum Junction-to-Case (Drain)                           | R <sub>thJC</sub>     | -  |                                      | 0.3                          | 8    |       | °C/W  |          |
|  |                       |  |                                      |                              |      |       |       |          |
| <b>SPECIFICATIONS</b> ( $T_J = 25 \text{ °C}$ , u          | nless otherw          | ise noted)   |                                      |                              |      |       |       |          |
| PARAMETER  | SYMBOL                | TES  | T CONDIT                             | IONS                         | MIN. | TYP.  | MAX.  | UNI      |
| Static   |                       | -  |                                      |                              |      | • •   |       | <u>.</u> |
| Drain-Source Breakdown Voltage                             | V <sub>DS</sub>       | V <sub>GS</sub> :  | = 0 V, I <sub>D</sub> =              | 1 mA                         | 500  | -     | -     | V        |
| V <sub>DS</sub> Temperature Coefficient                    | $\Delta V_{DS}/T_{J}$ | Referenc   | e to 25 °C,                          | I <sub>D</sub> = 1 mA        | -    | 0.70  | -     | V/°C     |
| Gate-Source Threshold Voltage (N)                          | V <sub>GS(th)</sub>   | V <sub>DS</sub> =  | = V <sub>GS</sub> , I <sub>D</sub> = | 250 µA                       | 2.5  | -     | 4.5   | V        |
|  |                       |  | $V_{GS} = \pm 20$                    | V                            | -    | -     | ± 100 | nA       |
| Gate-Source Leakage  | I <sub>GSS</sub>      |  | $V_{GS} = \pm 30$                    | ) V                          | -    | -     | ± 1   | μA       |
|  |                       |  | = 500V, V <sub>G</sub>               |                              | -    | -     | 1     |          |
| Zero Gate Voltage Drain Current                            | I <sub>DSS</sub>      | _  |                                      | v, T <sub>J</sub> = 125 °C   | -    | -     | 100   | μA       |
| Drain-Source On-State Resistance                           | R <sub>DS(on)</sub>   | V <sub>GS</sub> = 10 V   |                                      | I <sub>D</sub> = 11A         | -    | 0.085 | -     | Ω        |
| Forward Transconductance                                   | <b>g</b> fs           | V <sub>DS</sub>  | <sub>s</sub> = 30 V, I <sub>D</sub>  | = 11 A                       | -    | 5.6   | -     | S        |
| Dynamic  |                       |  |                                      |                              |      |       |       | 1        |
| Input Capacitance  | C <sub>iss</sub>      |  | V <sub>GS</sub> = 0 \                | /                            | -    | 3600  | -     |          |
| Output Capacitance   | Coss                  |  | $V_{DS} = 100$                       |                              | -    | 330   | -     | 1        |
| Reverse Transfer Capacitance                               | C <sub>rss</sub>      |  | f = 1 MH                             | Z                            | -    | 4     | -     |          |
| Effective Output Capacitance, Energy Related <sup>a</sup>  | C <sub>o(er)</sub>    |  | / to 500 \/                          |                              | -    | 63    | -     | pF       |
| Effective Output Capacitance, Time<br>Related <sup>b</sup> | C <sub>o(tr)</sub>    | $V_{DS} = 0 V \text{ to } 520 V, V_{GS} = 0 V$                           |                                      | -                            | 213  | -     | 1     |          |
| Total Gate Charge  | Qg                    |  |                                      |                              | -    | 148   | -     |          |
| Gate-Source Charge   | Q <sub>gs</sub>       | $V_{GS} = 10 V$  | I <sub>D</sub> = 20                  | 0 A, V <sub>DS</sub> = 520 V | -    | 39    | -     | nC       |
| Gate-Drain Charge  | Q <sub>gd</sub>       |  |                                      |                              | -    | 47    | -     |          |
| Turn-On Delay Time   | t <sub>d(on)</sub>    |  |                                      |                              | -    | 18    | 25    |          |
| Rise Time  | t <sub>r</sub>        | V <sub>DD</sub>  | = 520 V, I <sub>C</sub>              | ) = 20A,                     | -    | 24    | 55    | ns       |
| Turn-Off Delay Time  | t <sub>d(off)</sub>   | Vaa  | = 10 V, R <sub>q</sub>               | -910                         | -    | 80    | -     |          |
| Fall Time  | t <sub>f</sub>        |  | 0                                    |                              | -    | 12    | -     |          |
| Gate Input Resistance                                      | Rg                    | f = 1  | MHz, ope                             | n drain                      | -    | 0.8   | -     | Ω        |
| Drain-Source Body Diode Characteristic                     | S                     | 1  |                                      |                              |      |       |       |          |
| Continuous Source-Drain Diode Current                      | I <sub>S</sub>        | MOSFET symbol<br>showing the<br>integral reverse<br>p - n junction diode |                                      | -                            | 33   |       |       |          |
| Pulsed Diode Forward Current                               | I <sub>SM</sub>       |  |                                      | -                            | -    | 100   | A     |          |
| Diode Forward Voltage                                      | V <sub>SD</sub>       | T <sub>J</sub> = 25 °C, I <sub>S</sub> = 8 A, V <sub>GS</sub> = 0 V      |                                      | -                            | -    | 1.5   | V     |          |
| Reverse Recovery Time                                      | t <sub>rr</sub>       |  |                                      |                              | -    | 520   | -     | ns       |
| Reverse Recovery Charge                                    | Q <sub>rr</sub>       | $T_J = 2$  | 25 °C, I <sub>F</sub> =              | $I_{\rm S} = 8  {\rm A},$    | -    | 5.8   | -     | μC       |
| Reverse Recovery Current                                   | I <sub>RRM</sub>      | dl/dt = '  | 100 A/µs, \                          | $I_{\rm R} = 400  \rm V$     | _    | 4 5   | ļ     | A        |

#### Notes

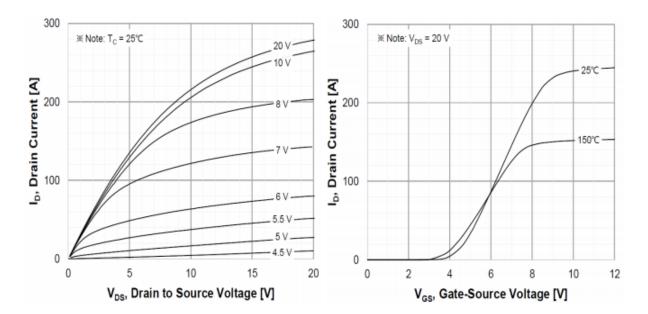
a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ . b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .



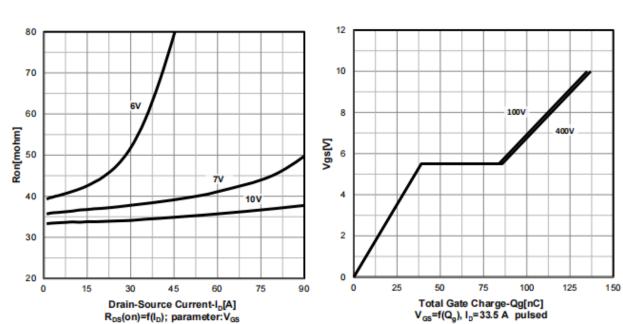


Typ. output characteristics  $T_i$ =25  $^{\circ}C$ 

Transfer characteristics



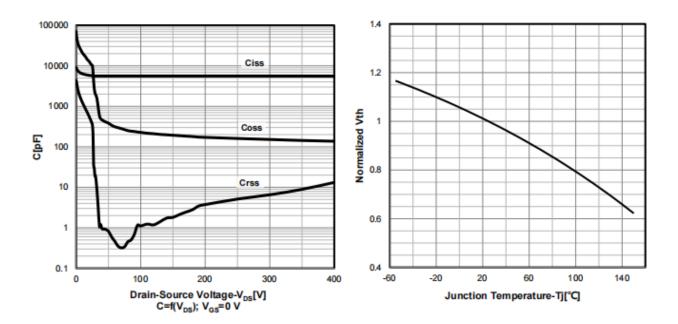




Typ. drain-source on-state resistance

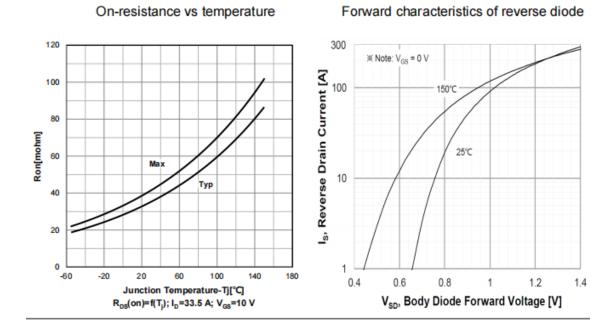
Typ. capacitances

Normalized V<sub>GS(th)</sub> characteristics



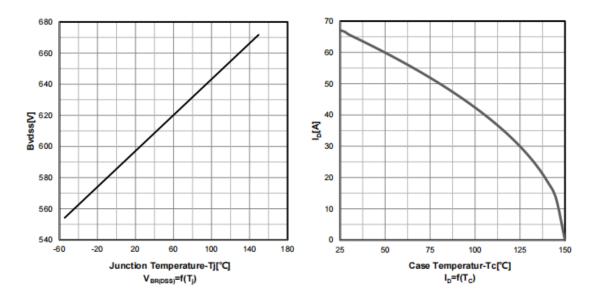
Typ. gate charge characteristics





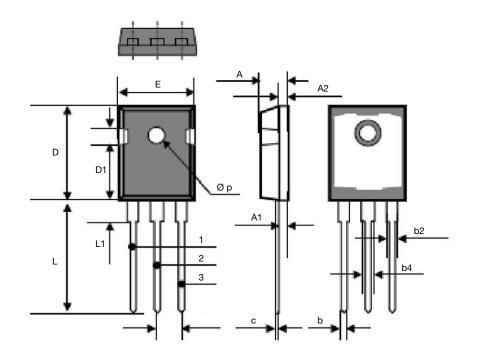
Drain-source breakdown voltage

Drain current vs temperature





TO-247



| DIM  | MILLIN   | METERS | INC       | HES   |  |
|------|----------|--------|-----------|-------|--|
| DIM. | MIN.     | MAX.   | MIN.      | MAX.  |  |
| А    | 4.70     | 5.31   | 0.185     | 0.209 |  |
| A1   | 2.21     | 2.59   | 0.087     | 0.102 |  |
| A2   | 1.50     | 2.49   | 0.059     | 0.098 |  |
| b    | 0.99     | 1.40   | 0.039     | 0.055 |  |
| b2   | 1.65     | 2.41   | 0.065     | 0.095 |  |
| b4   | 2.59     | 3.43   | 0.102     | 0.135 |  |
| С    | 0.61 BSC |        | 0.024 BSC |       |  |
| D    | 20.80    | 21.46  | 0.819     | 0.845 |  |
| D1   | 3.68     | 5.49   | 0.145     | 0.216 |  |
| (e)  | 5.46 BSC |        | 0.215 BSC |       |  |
| E    | 15.49    | 16.26  | 0.610     | 0.640 |  |
| L    | 19.81    | 20.32  | 0.780     | 0.800 |  |
| L1   | 4.06     | 4.50   | 0.160     | 0.177 |  |
| Øp   | 3.51     | 3.66   | 0.138     | 0.144 |  |



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